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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10070080	FILING DATE 07/01/2002	CLASS 257	SUBCLASS 121	GAU 1714	2818	EXAMINER TRATT, L.D. Nlu
**APPLICANTS: Do Bento Vieira Antonio; 438 112						
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/FR01/02367 08/24/2000						
** FOREIGN APPLICATIONS VERIFIED: FRANCE 99/11024 09/02/1999						
PG-PUB		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>		
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 97-GR2-144		
TITLE : Method for packaging a semiconductor chip containing sensors and resulting package U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)						

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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